

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	POWER AND DISCRETES/26/16536
1.3 Title of PCN	HU3PAK SiC MOSFET Gen 3: Back End introduction at Bouskoura (BSK) _ Morocco on top of the actual ATJ JAPAN on new 8 inches Front End FABs with wire bonding optimization.
1.4 Product Category	Pls Refer to the impacted Product list. (BBRF7A1, BRI9A1, BVJ7A1/BRJ7A1)
1.5 Issue date	2026-08-07

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Angelo RAO
2.1.2 Marketing Manager	Francesco FISICHELLA
2.1.3 Quality Manager	Massimiliano CUOZZO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Product transfer from one site to another site, even if test or process line is qualified	- CW8F/SiC Campus and SSTF/Sanan as Front End Plants - ATJ/Japan and BSK/Marocco as Back End Plants

4. Description of change

	Old	New
4.1 Description	HU3PAK production - CTWF/Catania FE 6" as Front End Plant - ATJ/Japan BE Plant - Source Wire Bonding diagram 2x10mils or 4x7mils	HU3PAK production - CW8F/SiC Campus and SSTF/Sanan as Front End Plants - BSK/Marocco - Source Wire Bonding diagram 4x10mils
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Capacity Extension
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	by FGs
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7. Timing / schedule

7.1 Date of qualification results	2027-01-15
7.2 Intended start of delivery	2027-01-29
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)		
16536 Public product.pdf 16536 HU3PAK - BSK introduction in 8 inches manufacturing locations.pdf 16536 HU3PAK_BSK BE introduction and BSK_ATJ source wire bonding optimization for 8 inches_Rev3 2.pdf		

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SCT040HU120G3AG	
	SCT040HU65G3AG	
	SCT070HU120G3AG	

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